Cost per unit

time

yield > time

Manufacturing costs drop as expertise grows, for that process

- -- better methods
- -- better equipment
- -- less waste (time, materials)

Yield% = (1 - waste%)

new plant online: \$3B/3 yr

- -- #(devices **sellable**) **versus** #(devices **produced**)
- -- #(devices sellable) versus (cost to produce them)

E.g. DRAM => price = a cost

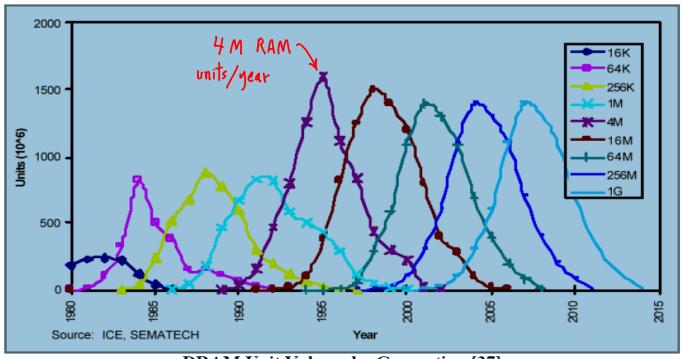
80% contract sales to large Equipment makers (hidden)

20% open market

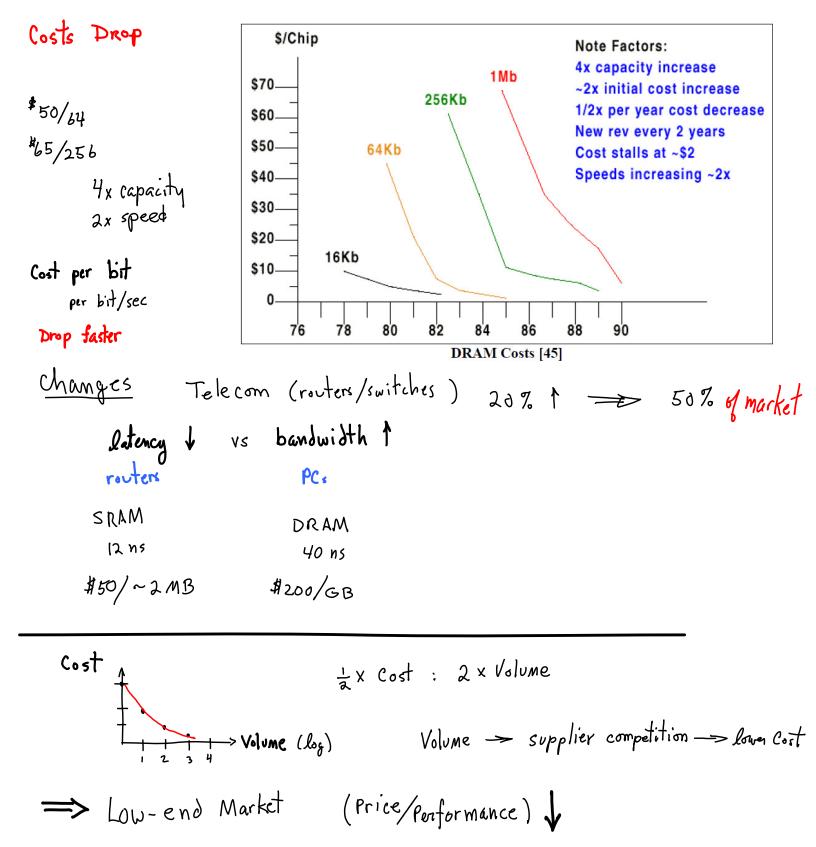
Total Capacity

PRICE

--many vendors
---same items



DRAM Unit Volume by Generation [37]



Standardization / Volume ====> market acceptance of innovations

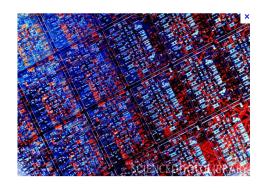
Cloud Pricing AWS Combined efficiencies

											, bottomed out				
	Description	Туре	CU	Original \$ /	Current \$	% Reduction	Aug 2006	Oct 2007	May 2008	Oct 2009	Feb 2010	<u>July</u> 2010	<u>Sep</u> 2010	Nov 2010	Nov 2011
	Small - "the original"	m1.small	1	\$0.10	\$0.085	15%	\$0.10			\$0.09					_
7	Large	m1.large	4	\$0.10	\$0.085	15%		\$0.40		\$0.34	-	- Pr	ice		
	Extra Large	m1.xlarge	8	\$0.10	\$0.085	15%		\$0.80		\$0.68		Re	duction	S	
	High-CPU Medium	c1.medium	5	\$0.04	\$0.03	15%			\$0.20	\$0.17					
	High-CPU Extra Large	c1.xlarge	20	\$0.04	\$0.03	15%			\$0.80	\$0.68					
	High-Memory Double Extra Large	m2.2xlarge	13	\$0.09	0.077	17%				\$1.20			\$1.00		
	High-Memory Quad Extra Large	m2.4xlarge	26	\$0.09	0.077	17%				\$2.40			\$2.00		
(High Memory Extra Large	m2.xlarge	6.5	\$0.12	> 0.077	33%					\$0.75				
	Cluster Compute	cc1.4xlarge	33.5	\$0.05	\$0.04	19%						\$1.60			
	Cluster Compute Eight Extra Large	cc2.8xlarge	88	\$0.03	\$0.03	0%									\$2.40
	Micro	t1.micro	0.9	\$0.02	\$0.02	0%							\$0.02		
	Cluster GPU Instance	cg1.4xlarge	33.5	\$0.06	\$0.06	0%								\$2.10	

CPUs, Chips, soc

Si ingots slicing - waters

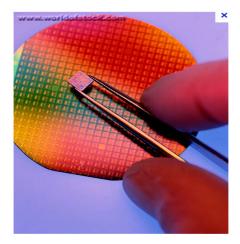




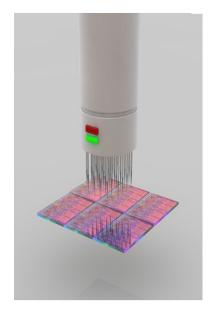
dicing

masking, etching, doping

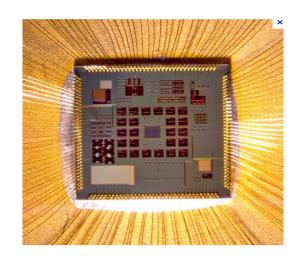




Circuit testing

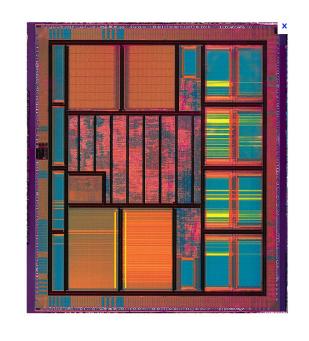


Pad Bonding

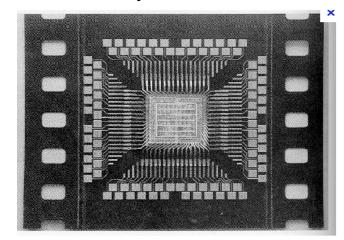




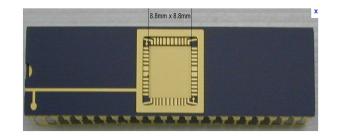
board printing mounting

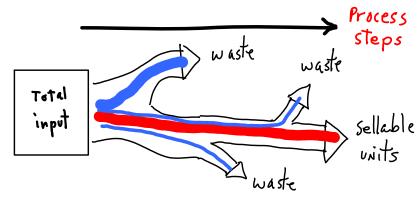


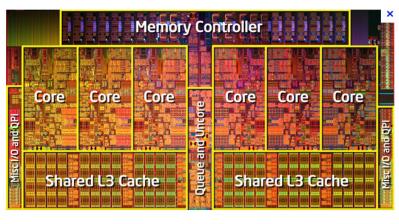
Pin Packaging



| encasing







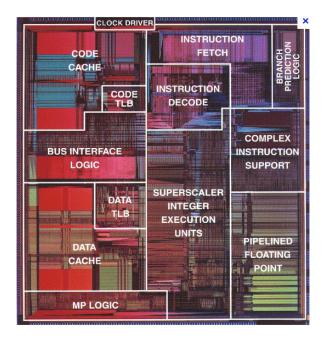
i7

$$\frac{\text{Hies}}{\text{Hies}} = \left(\frac{\text{Area water}}{\text{Area}_{\text{die}}}\right) - \left(\frac{\text{Circumference water}}{\text{Diagonal}_{\text{die}}}\right)$$

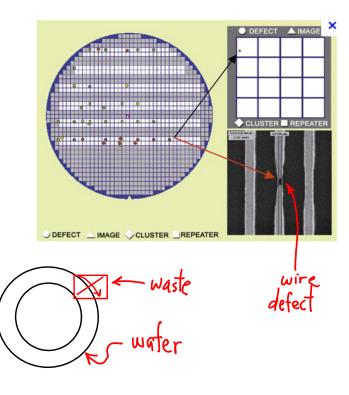
$$= \frac{\text{Tr}^2}{\text{Adie}} - \frac{2\text{Tr}}{\sqrt{2}\sqrt{\text{Adie}}}$$

yield
$$\simeq \frac{\%(good wafers)/\%(wafers)}{\left[1 + \frac{\%(defects)}{c m^2}(A_{die}cm^2)\right]^N}$$

Curre fitting for particular process >> N & [11.5, 15.5]



P5





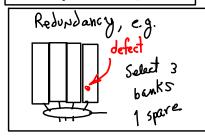
$$\frac{\times (\text{defeds})}{\text{cm}^2} \approx \frac{0.04}{\text{E}}$$
 function of time + volume

$$A_{die} = 2.25 \text{ cm}^2 \implies 109$$

$$A_{die} = 1 \text{ cm}^2 \implies 424$$

#13

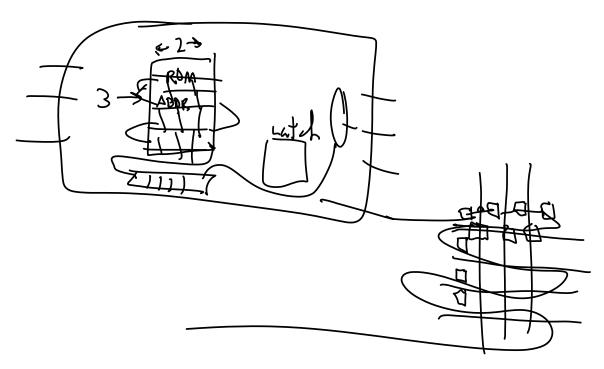
\$0.1



to our purposes

$$\Rightarrow$$
 yield =
$$\frac{1}{\left[1 + \left(\frac{\text{defects}}{\text{cm}^2}\right) \frac{\text{A}_{\text{Jie}}}{\text{A}}\right]^2}$$

FPGA



E. G.

#/wafer = \$1,500

Wafer size = 200 mm
$$\Rightarrow A = \pi r^2 = 3 \times 10^4 \text{ cm}^2$$

#(defects/cm²) = 0.031

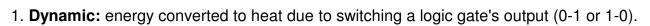
die size = (1 cm) x (1 cm) = 1 cm²

yield = $\frac{1}{1+(0.031)} A_{die/2}^2 = \frac{1}{1+(0.03)} 50 = \frac{1}{2.55}^2 = \frac{1}{2.4}$

*dies gand = $\frac{A_{wafer}}{A_{die}} = \frac{3 \times 10^4}{10^2} = \frac{300}{125} = 125$

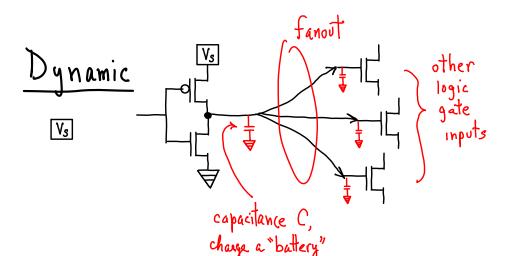
#/die gand = $\frac{4}{4} = \frac{4}{125} = \frac{4}{125$

CMOS power and energy consumption





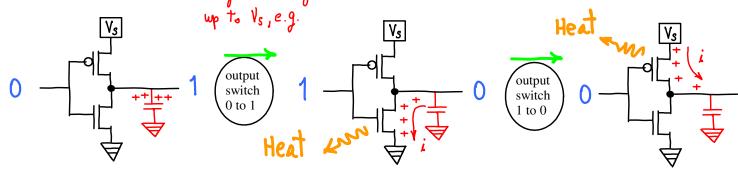
2. Static: energy converted to heat due to (steady) leakage currents.



CR_{max}
$$\propto$$
 V

Speed of charging C

 $\longrightarrow E = \frac{1}{4}$
 $e^{-} \longrightarrow acceleration$
 $\sim gravity$



$$\frac{\overline{Joules}}{sec} = power = V(\frac{1}{sec}) = Vi = (iR)i$$

R Transistor

$$E = \frac{J_{60}les}{Sec}(\Delta t sec) = \frac{1}{2}CV^{2}$$

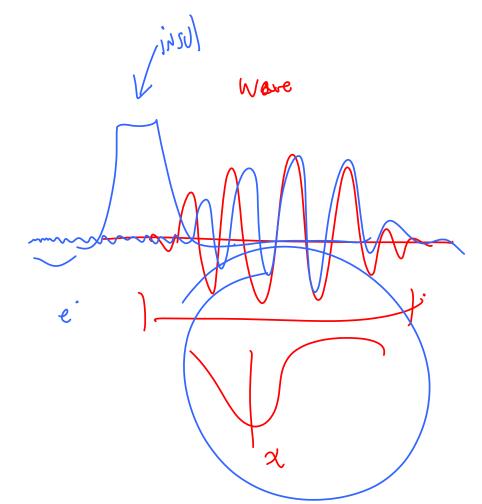
$$\frac{\left(E\right)_{\text{Transistor}}}{0.1-\text{Switch}} = \frac{1}{2} C_{\text{Transistor}} V^{2}$$

$$\frac{E_{\text{ToTal}}}{Switch} = \sum_{i} \frac{1}{2} C_{i} V^{2} = \frac{1}{2} V^{2} \sum_{i} C_{i} = \frac{1}{2} V^{2} C_{\text{ToTal-chip}}$$

Power =
$$\left(\frac{E_{ToTal}}{S_{witch}}\right)\left(\frac{S_{witch}}{S_{ec}}\right) = \frac{E_{ToTal}}{S_{witch}} CR$$

TR switching the

QM waves



E.G.
$$C_{Total}^{new} = 0.85 C_{Total}^{old}$$

$$V^{\text{new}} = 0.85 V^{\text{old}}$$

$$\frac{CR_{\text{new}}}{CR_{\text{old}}} = \frac{kV_{\text{new}}}{kV_{\text{old}}} = \frac{0.85 \text{ V}_{\text{old}}}{V_{\text{old}}}$$

CR & V

$$= \frac{\rho_{\text{ower}_{\text{new}}}}{\rho_{\text{ower}_{\text{old}}}} = \frac{\binom{1/2}{2} C_{\text{Total}}^{\text{new}} V_{\text{new}}^2 C R_{\text{new}}}{\binom{1/2}{2} C_{\text{Total}}^{\text{old}} V_{\text{old}}^2 C R_{\text{old}}}$$

$$= \frac{\left(0.85 C_{ToTal}^{old}\right) \left(0.85 V_{\bullet 1\delta}\right)^{2} \left(0.85 C_{\bullet 1\delta}\right)}{C_{ToTal}^{old} V_{\bullet 1\delta}^{2} C_{\bullet 1\delta}}$$

$$= (0.85)^{4} = 52\%$$

$$\frac{\mathsf{E}_{\mathsf{new}}}{\mathsf{E}_{\mathsf{old}}} = \frac{k_{\mathsf{switches}} \; \mathsf{E}'_{\mathsf{switch}}}{k_{\mathsf{switches}} \; \mathsf{E}'_{\mathsf{switch}}} = \frac{k_{\mathsf{a}} \; \mathsf{C}^{\mathsf{hew}} \; \mathsf{V}_{\mathsf{new}}^{\mathsf{2}}}{k_{\mathsf{a}} \; \mathsf{C}^{\mathsf{old}} \; \mathsf{V}_{\mathsf{old}}^{\mathsf{2}}} = \frac{(0.85 \; \mathsf{C}^{\mathsf{old}})(0.85 \; \mathsf{V}_{\mathsf{old}})^{\mathsf{2}}}{\mathsf{C}^{\mathsf{old}} \; \mathsf{V}_{\mathsf{old}}^{\mathsf{2}}}$$

$$= (0.85)^3 = 61\%$$

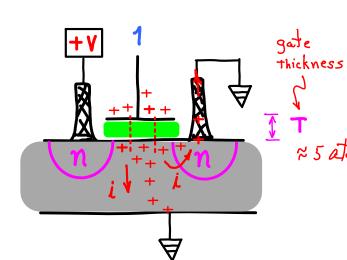
Static

leakage

E

solicon

substrate



now greater than dynamic power

year
1985 1990 1995 2000 2005 2010
1% 5% 7% 20% 30% 60% Crate of change

Geometric Mean

what's the average rate?

What rate would give the same overall change over the entire time period?

$$r_1 = \frac{5}{1}$$
 $r_2 = \frac{7}{5}$

$$r_3 = \frac{20}{7}$$

$$r_1 = \frac{5}{1}$$
 $r_2 = \frac{7}{5}$ $r_3 = \frac{20}{1}$ $r_4 = \frac{30}{20}$ $r_5 = \frac{10}{30}$

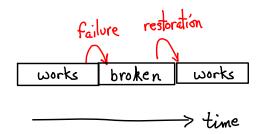
$$\overline{r} = \left(\frac{n}{11}r_{\cdot}\right)^{n} = \left(\frac{60}{1}\right)^{5} \cong 2.3 \text{ pm 5 yens}$$

Prediction for 2015?
$$\overline{r}$$
 (60%) = 2.3 (60%) = 1.38%

Static power exceeds dynamic by 38%!

failures, systemic, hierarchic

Service Accomplishment = it works Service Interruption = broken



Reliability = time to failure

Failure Rate =
$$\frac{1}{MTTF}$$
 (expected #failures in a year, e.g.)

Mean Time Between Failures (MTBF) = MTTF + MTTR

Availability = $\frac{1}{MTBF}$ time working = $\frac{MTTF}{MTBF}$

Multi-level
Recovery
- error correction
- redo
- redo

Assume: exponentially dist. failures

- independent of t, time of experiment

- No dependency between components $E(\# \text{ Failures in } \Delta T) = \mu \Delta T$ 1 failure

1 = $\mu \overline{\Delta T_1}$ ang time to 1st fail $\mu T = \overline{\Delta T_1} = \frac{1}{\mu}$

$$\mu = \sum_{i} \mu_{i} = \sum_{i} \left(\frac{1}{M\pi} f_{i} \right)$$
Assume devices fail independently:
$$P(F_{1} \text{ or } F_{2}) = P(F_{1}) + P(F_{2})$$

$$= \left(10 + 2 + 5 + 5 + 1 \right) / M h_{\Gamma} = \frac{23}{M} h_{\Gamma}$$

$$MTTF = \frac{1}{\mu} = \frac{10^{6} \text{ hr}}{23}$$

$$= \left(\frac{10^{2}}{25} \right) 10^{4} = 40,000 \text{ hr}$$

$$= \frac{10^{6} \text{ hr}}{23}$$

$$= \left(\frac{10^{2}}{25} \right) 10^{4} = 40,000 \text{ hr}$$

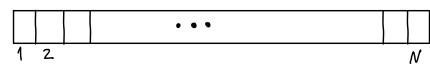
$$= \left(\frac{10^{2}}{25} \right) \left(\frac{24 \text{ hr}}{3} \right)$$

$$= \left(\frac{400}{250} \right) \left(\frac{100}{4} \right)$$

$$= 10,000$$

E.g., 2 power supplies?

Jet's add a redundant power supply: if one fails we fix it while the other keeps working. How long before the system fails: it happens that before we finish the repair, the backup also breaks?



Prob(fails at i) = $p^{i}(1-p)^{i}$ fails at i+1

$$E(i) = \sum_{k=1}^{N} k \operatorname{Prob}(fails at k)$$

$$= \sum_{k=1}^{N} k p^{k} (1-p) = (1-p) \sum_{k=1}^{N} k p^{k}$$

$$= (1-10) \sum_{k=0}^{N} k \cdot 10^{k}$$

$$= (1-p) \sum_{k=1}^{N} \frac{\partial}{\partial p} p^{k+1} = (1-p) p \frac{\partial}{\partial p} \sum_{k=1}^{N} p^{k}$$

$$\cong (1-p) p \frac{\delta}{\delta p} \frac{1}{(1-p)} = (1-p) p/(1-p)^2$$

$$= p/(1-p) = MTTF$$

Example

Suppose
$$Prob(Jail) = (1-p) = \frac{1}{2^m}$$

 $MTTF = \frac{p}{(1-p)} = \frac{(1-\frac{1}{2^m})}{(\frac{1}{2^m})} = 2^m - 1$

2 Power Supplies

$$Prob(both work) = p^2$$

$$Prob(both work) = p^2$$
 \longrightarrow $Prob(not both working) = (1-p^2)$

$$\text{MTTF}_{\mathbf{z}} = \text{P}^{2}_{(1-p^{2})} = \text{P}^{2}_{(1-p)(1+p)} = \frac{p}{(1-p)(1+p)}$$

$$= M TTF \frac{P}{(I+P)} \} for P large \cong \frac{1}{2} M TTF$$

A Model

Suppose N time periods, each of unit length. N is large so that no devices every survive to age N+1.

Each time period, flip a coin:

Prob(fails) =
$$(1 - p)$$

What's the probability the 2nd fails in MTTR? Time independent = begin as if only one power supply.

Looked at another way

Total time = TN intervals, $dt = \frac{T}{N}$

Prob (fail in dt) =
$$\frac{1}{N}$$

N 7

Prob(fails in interval of length L = ndt) $\frac{n}{n}$

$$\sum_{i}^{n} P_{rob}(f_{ai}| \text{ in } dt_{i}) = \sum_{i}^{n} (\%) = \%$$

$$= \frac{L/dt}{T/dt} = \frac{L}{T} \implies \text{ uniform } dist.$$

$$Prob(fail in MTTR) = \frac{MTTR}{T} = \frac{MTTR}{2 MTTF}$$

 $1/1_{2MTTF} = \mu$, averge rate of failures for 2 power supplies

repaired in time
$$\begin{cases} \text{average } % \\ \text{failed to} \\ \text{repaired in time} \end{cases} = \frac{\text{Prob}(\text{fail to rapair})}{\text{before } 2^{nd} \text{ fail}} = \frac{\text{MTTR}}{2 \text{ MTTF}}$$

rate of system failures = M (% not repaired)

$$= \frac{1}{(1/2 \text{ MTT F})} \left(\frac{\text{MTTR}}{2 \text{ MTTF}} \right) = \frac{\text{MTTR}}{\text{MTTF}^2}$$

$$\frac{MTF^{2}}{MTF^{2}} = \frac{24}{(5M)^{2}} \approx \frac{25^{2}}{10^{12}} = \frac{(100/4)^{2}}{10^{12}} = \frac{10^{4}}{16 \cdot 10^{12}} = \frac{1}{16 \cdot 10^{8}}$$

$$= \frac{1}{16 \cdot 10^{4}} = \frac{100}{16 \cdot 10^{12}} = \frac{100}{16 \cdot 10^{12}} = \frac{1}{16 \cdot 10^{12$$

on average, w/104 systems, 1 fail in 16 yrs.

Poisson

Bernoulli w/
$$p = \frac{\lambda}{\lambda} dt$$

Prob(m, N, p) =
$$\binom{N}{m} p^m q^{N-m}$$

approx.
$$\Rightarrow \frac{e^{-pN}(pN)^m}{m!}$$

Let
$$pN = \lambda$$

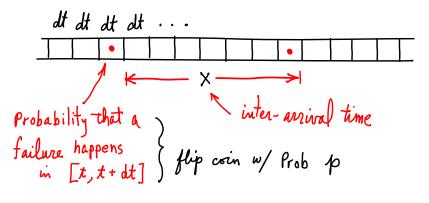
$$\operatorname{Prob}(m,\lambda) = \frac{e^{-\lambda t}(\lambda t)^m}{m!}$$
, $\lambda = \operatorname{rate} \operatorname{Prob}(k \text{ events in time } t)$

$$\operatorname{Prob}(X_1 \leq x) = |-e^{-\lambda x}|$$

$$E(X) = \frac{1}{\lambda}$$
 define λ

Prob(arrival time t = 5 | one event)

$$= \frac{5}{t}$$
 uniform dist.



Prob

Prob(time of next arrival $\leq \chi$)

Price Performance

Basic measure: operations/#

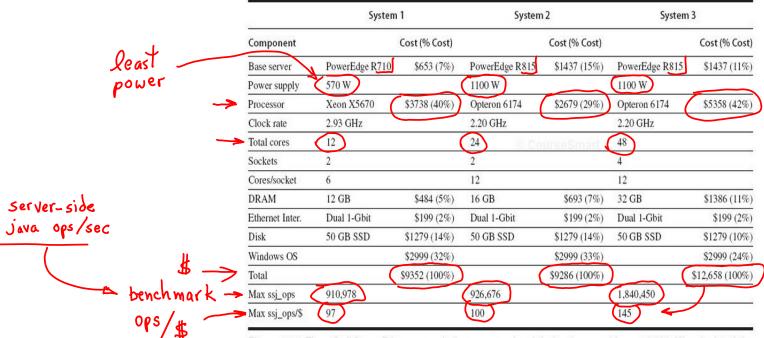


Figure 1.18 Three Dell PowerEdge servers being measured and their prices as of August 2010. We calculated the cost of the processors by subtracting the cost of a second processor. Similarly, we calculated the overall cost of memory by seeing what the cost of extra memory was. Hence, the base cost of the server is adjusted by removing the estimated cost of the default processor and memory. Chapter 5 describes how these multi-socket systems are connected together.

ops/watt vs load

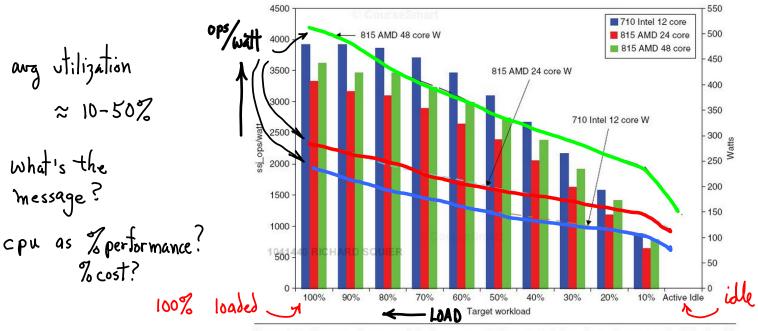


Figure 1.19 Power-performance of the three servers in Figure 1.18. Ssj_ops/watt values are on the left axis, with the three columns associated with it, and watts are on the right axis, with the three lines associated with it. The horizontal axis shows the target workload, as it varies from 100% to Active Idle. The Intel-based R715 has the best ssj_ops/watt at each workload level, and it also consumes the lowest power at each level.